

**BINDER FOR THICK-FILM PASTE**

**Patent number:** JP10036479  
**Publication date:** 1998-02-10  
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**Classification:**  
- **international:** C08G18/48; C08G63/66; C08L67/02; C08L75/08;  
H05K1/09  
- **european:**  
**Application number:** JP19960193407 19960723  
**Priority number(s):**

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**Abstract of JP10036479**

**PROBLEM TO BE SOLVED:** To obtain a binder for thick-film pastes which remains no carbon even when baked in the atmosphere, a low-temperature range or an inert gas atmosphere by using a specified high-molecular compound having a specified average molecular weight or higher.  
**SOLUTION:** A dihydroxy compound having an average molecular weight of 1,000 or above and obtained by the addition polymerization of an alkylene oxide is reacted with a dicarboxylic acid, its anhydride or its lower alkyl ester or reacted with an isocyanate-terminated compound to obtain an ester-bond-containing or a urethane-bond-containing polymer compound having an average molecular weight of 20,000 or above. It is desirable that the polymer compound has 50wt.% or above alkylene oxide. The polymer compound is used as a binder for thick-film pastes.

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